

Dual N-Channel 100V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a			
100	0.018at V _{GS} = 10 V	35			
100	0.022at V _{GS} = 4.5 V	36			

FEATURES

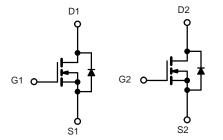
- 175 °C Junction Temperature
- Trench technology Power MOSFET
- Material categorization:







Top View



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V_{GS}	±20	V			
Continuous Drain Current (T,I = 175 °C) ^b	T _C = 25 °C	I_	35			
Continuous Drain Current (1 _J = 175 °C) ²	T _C = 100 °C	· I _D	20 ^a			
Pulsed Drain Current	I _{DM}	105	А			
Continuous Source Current (Diode Conduction)	I _S	76 ^a				
Avalanche Current	I _{AS}	82				
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	110	mJ		
Maximum Power Dissipation	T _C = 25 °C	P _D	136	W		
Maximum Fower Dissipation	T _A = 25 °C	' D	3 ^b , 8.3 ^{b, c}] vv		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R_{thJA}	15	18	°C/W		
waximum Junction-to-Ambient	Steady State		60	50			
Maximum Junction-to-Case		R_{thJC}	0.85	1.1			

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



SPECIFICATIONS ($T_J = 25$	°C, unless o	otherwise noted)					
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 30V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 175 °C$			250		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	60			Α	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.018			
Desir Occurs Oc Otata Basistanah	P	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010			
		V _{GS} = 4.5 V, I _D = 12A		0.022			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
Dynamic							
Input Capacitance	C _{iss}	S		3900			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}$		470		pF	
Reverse Transfer Capacitance	C _{rss}			225			
Total Gate Charge ^c	Q_g			89	70		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		26		nC	
Gate-Drain Charge ^c	Q_{gd}			23			
Turn-On Delay Time ^c	t _{d(on)}			21	25		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_L = 0.6 \Omega$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		15	25	ns	
Turn-Off Delay Time ^c	t _{d(off)}			35	50	115	
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)					
Pulsed Current	I _{SM}				105	Α	
Diode Forward Voltage	V_{SD}	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		4	135	ns	

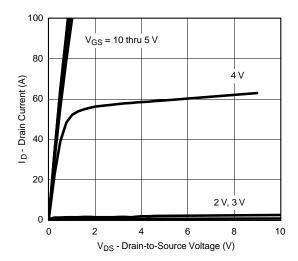
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

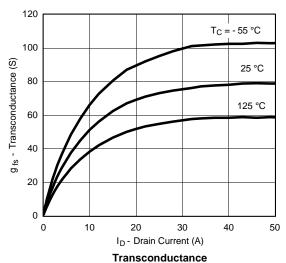
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



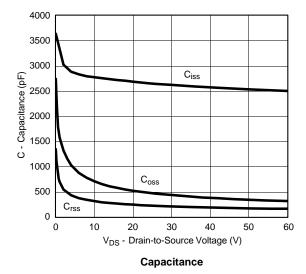
TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics

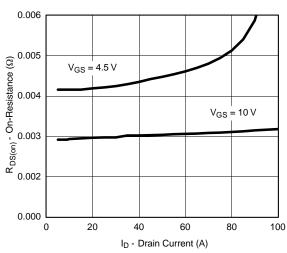


Transconductano

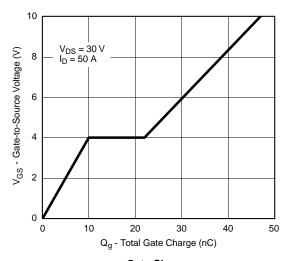


100 80 (Y) uipu 60 T_C = 125 °C 25 °C 0 1 2 3 4 5

V_{GS} - Gate-to-Source Voltage (V) Transfer Characteristics



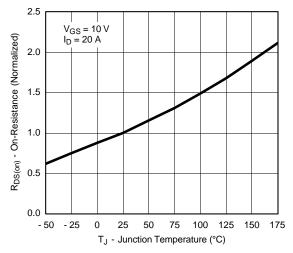
On-Resistance vs. Drain Current



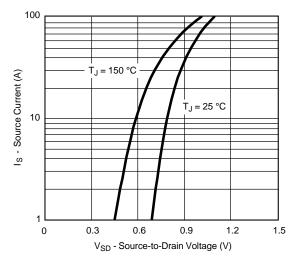
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

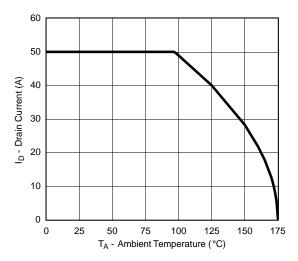


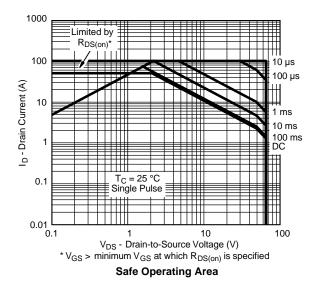
Source-Drain Diode Forward Voltage



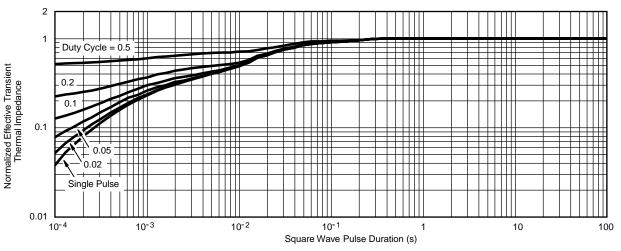
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THERMAL RATINGS





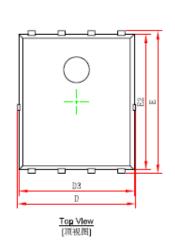
Maximum Drain Current vs. Ambient Temperature

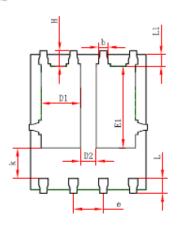


Normalized Thermal Transient Impedance, Junction-to-Case



PDFNWB5×6-8L-A PACKAGE OUTLINE DIMENSIONS





Bottom View [背视图]

Dimensions In Inches

0.050TYP.

0.028

0.023

0.029

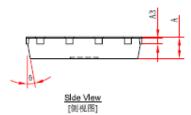
12°

0.022

0.017

0.023

10°



е

L1

Н

θ

NAME OF TAXABLE PARTY.				
Symbol	Min.	Max.	Min.	Max.
Α	0.900	1.000	0.035	0.039
A3	0.254 REF.		0.010	REF.
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
h	0.350	0.450	0.014	0.018

0.711

0.576

0.726

12°

Dimensions In Millimeters

1.270TYP

0.559

0.424

0.574

10°



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